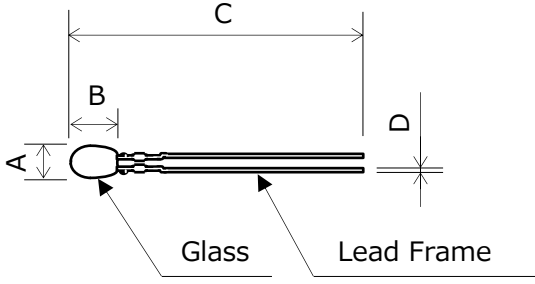
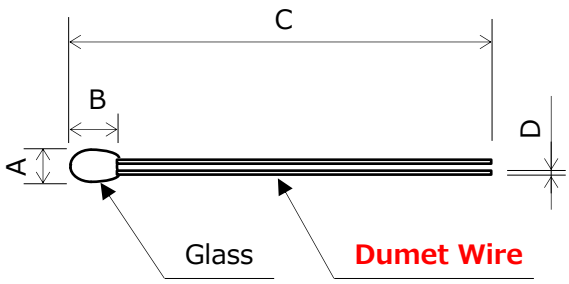
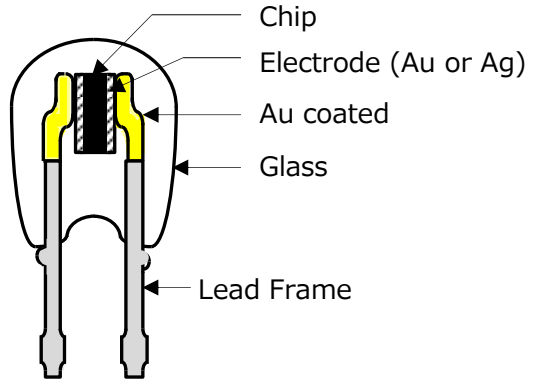
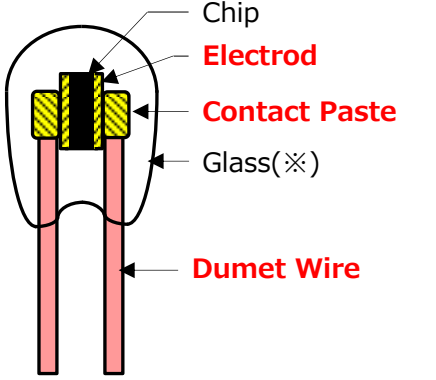


GT-2 & NT-4 Comparison Chart

EN: KH - SUS

1. GT-2 and NT-4 comparison chart on Table 1 below

Table 1. GT-2 and NT-4 Comparison Chart

Product name		GT-2	NT-4
Rating	Dissipation Factor	Appx 0.6mW/°C (in still air)	Appx 0.8mW/°C (in still air)
	Thermal Time Constant	appx 7 sec (in still air)	Appx 6 sec (in still air)
	Operating Temp Range	-50°C ~ +300°C	-50°C ~ +300°C
	Max Power Dissipation	3mW at 25°C (Temp rises appx 5°C due to self-heating)	4mW at 25°C (Temp rises appx 5°C due to self-heating)
Appearance and Dimensions	Appearance		
	Dimension A	1.35mm ±0.15mm	1.25mm ±0.30mm
	Dimension B	3.0mm ±1.0mm	2.5mm ±0.4mm
	Dimension C	48.0mm ±1.0mm	70.0mm ±2.0mm
	Dimension D	□ (0.18mm) × (0.15mm)	φ 0.20mm ±0.02mm
Glass Part	Interior Structure		
		※ Glass is the same as GT-2	

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Table 1. GT-2 and NT-4 Comparison Chart

Product Name		GT-2	NT-4	
Reliability	Test Criteria	Top Row: Testing Condition		
		Bottom Row: Review Standard		
Electrical Properties	Insulation Resistance	Apply DC 500V		
		100MΩ or more		
	Voltage Tolerance	Apply AC 500V for 1 minute		
		No more than 1mA of current		
Mechanical Properties	Terminal Tensile Strength	Pull the terminal towards the axis with 1N pull and hold for 10 seconds		
	Terminal Bend	Apply 0.5N load to the lead frame (dumet wire)		
		Bend 90°, then bend it back to original position. Bend 90° once in the opposite direction too		
	Free Fall	Drop from 1m height on maple wood board 3 times		
		Within ΔR25±2%, ΔB25/85±2%		
	Soldering Properties	Apply the appropriate flux and dip it in +245°C solder bath for 2 to 3 seconds		
Solder deposit ratio of 75% or more		Solder deposit ratio of 90% or more		
Solder Heat Res (soldering flow)	Dip the lead frame (dumet wire) in solder bath of +260°C for 10 seconds			
Environment Performance	Low Temp	-50°C / 1000hr	-55°C / 1000hr	
		ΔR25±2%、ΔB25/85±2%		
	High Temp	+300°C / 1000hr		
		Within ΔR25±2%, ΔB25/85±2%		
	Thermal Cycle (Air)	-30°C 5min→Rom Temp 3min→+200°C 5min→Room Temp 3min/ 5cycle		
		Within ΔR25±2%, ΔB25/85±2%		
	Thermal Shock (Liquid)	-30°C 3min→+150°C 3min / 1000cycles		
		Within ΔR25±2%, ΔB25/85±2%		
	Damp Heat	+70°C、RH90~95% / 1000hr		
		Within ΔR25±2%, ΔB25/85±2%		
Damp Heat (Load)	+70°C、RH90~95%、DC 0.1mA / 1000hr	+85°C、RH85%、DC 0.1mA / 1000hr		
	Within ΔR25±2%, ΔB25/85±2%			
Pressure Cooker			+121°C、2 atm、RH90~100% / 100hr	
			Within ΔR25±2%, ΔB25/85±2%	

※1 NT-4 goes through more severe thermal shock tests than the thermal cycle

※2 NT-4 goes through more severe damp heat load test than the damp heat test

※3 NT-4 goes through the pressure cooker test to put it at a higher standard than the GT-2